# **MP2664**



# 500mA, 5V USB, I<sup>2</sup>C-Controlled Battery Charger with Power Path Management for Single-Cell Li-Ion Battery in QFN Package

## **DESCRIPTION**

The MP2664 is a highly integrated, single-cell, Li-ion/Li-polymer battery charger with system power path management for space-limited, portable applications. The MP2664 uses input power from either an AC adapter or a USB port to supply the system load and charge the battery independently. The charger features constant current pre-charge, constant current fast-charge (CC) and constant voltage (CV) regulation, charge termination, and charge status.

The power path management function ensures continuous power to the system by automatically selecting the input, the battery, or both to power the system. This power stage features a low dropout regulator from the input to the system and a  $100m\Omega$  switch from the battery to the system. Power path management separates the charging current from the system load, which allows for proper charge termination and keeps the battery in full-charge mode.

The MP2664 provides system short-circuit protection (SCP) by limiting the current from the input to the system and the battery to the system. This feature is especially critical for preventing the Li-ion battery from being damaged by excessively high currents. An onchip battery under-voltage lockout (UVLO) cuts off the path between the battery and the system if the battery voltage drops below the programmable battery UVLO threshold, which prevents the Li-ion battery from being overdischarged. An integrated I<sup>2</sup>C control interface allows the MP2664 to program the charging parameters, such as input current limit, input voltage regulation limit, charging current, battery regulation voltage, safety timer, and battery UVLO.

The MP2664 is available in a QFN-10 (2mmx2mm) package.

#### **FEATURES**

- Fully Autonomous Charger for Single-Cell Li-Ion/Li-Polymer Batteries
- Complete Power Path Management for Simultaneously Powering the System and Charging the Battery
- ±0.5% Charging Voltage Accuracy
- 13V Maximum Voltage for the Input Source
- I<sup>2</sup>C Interface for Setting Charging Parameters and Status Reporting
- Fully Integrated Power Switches and No External Blocking Diode Required
- Built-In Robust Charging Protection Including Battery Temperature Monitoring and Programmable Timer
- PCB Over-Temperature Protection (OTP)
- System Reset Function
- Built-In Battery Disconnection Function
- Thermal Limiting Regulation On-Chip
- Available in a QFN-10 (2mmx2mm) Package

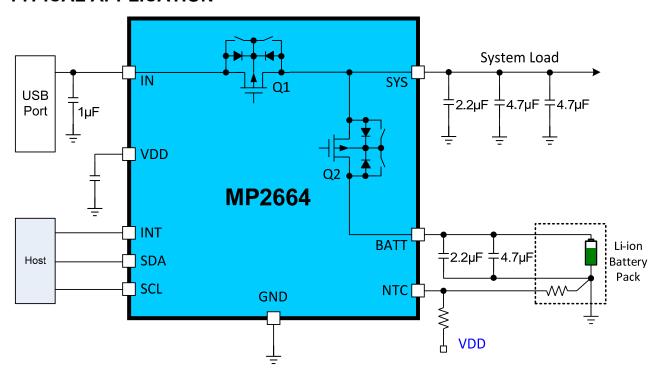
# **APPLICATIONS**

- Wearable Devices
- Smart Handheld Devices
- Fitness Accessories
- Smart Watches

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# **TYPICAL APPLICATION**





## ORDERING INFORMATION

Part Number*	Package	Top Marking
MP2664GG-xxxx**	QFN-10 (2mmx2mm)	See Below
EVKT-MP2664	Evaluation Kit	See Below

<sup>\*</sup> For Tape & Reel, add suffix –Z (e.g.: MP2664GG-xxxx–Z).

# **TOP MARKING**

HVY

LLL

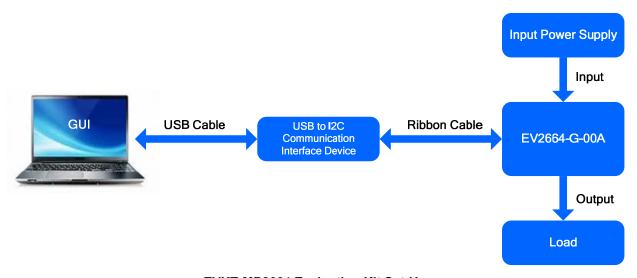
HV: Product code of MP2664GG

Y: Year code LLL: Lot number

## **EVALUATION KIT EVKT-MP2664**

EVKT-MP2664 Kit contents: (Items below can be ordered separately)

#	Part Number	Item	Quantity
1	EV2664-G-00A	MP2664 evaluation board	1
2	EVKT-USBI2C-02-Bag	Includes one USB to I2C communication interface device, one USB cable, one ribbon cable	1
3	Online resources	Includes: Datasheet, User guide, Product brief, and GUI	1

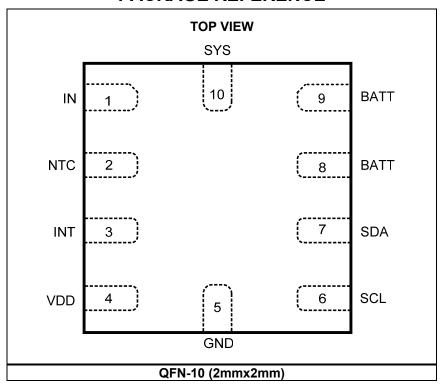


**EVKT-MP2664 Evaluation Kit Set-Up** 

<sup>\*\*&</sup>quot;xxxx" is the register setting option. The factory default is "0000." This content can be viewed in the I<sup>2</sup>C register map. Please contact an MPS FAE to obtain an "xxxx" value.



# **PACKAGE REFERENCE**



# **PIN FUNCTIONS**

Package Pin #	Name	I/O	Description		
1	IN	Power	<b>Input power.</b> Place a ≥1μF ceramic capacitor from IN to GND as close to the IC as possible.		
2	NTC	I	<b>Temperature sense input.</b> Connect a negative temperature coefficient thermistor to NTC. Program the hot and cold temperature window with resistor divider from VDD to NTC to GND. The charge is suspended when NTC is out of range.		
3	INT	0	<b>Open-drain interrupt output.</b> INT can send the charging status and fault interruption to the host. INT is also used to disconnect the system from the battery. Pull INT from high to low for >16s. The battery MOSFET is off and turns on automatically after >4s regardless of the INT state. The external pull-up resistor at INT should <i>not</i> be smaller than $300kΩ$ .		
4	VDD	I	Internal control power supply. Connect a 0.1µF ceramic capacitor from VDD to GND. No external load is allowed.		
5	GND	Power	Ground.		
6	SCL	I/O	I <sup>2</sup> C interface clock. Connect SCL to the logic rail through a 10kΩ resistor.		
7	SDA	I/O	<b>I<sup>2</sup>C interface data</b> . Connect SDA to the logic rail through a 10kΩ resistor.		
8, 9	BATT	Power	<b>Battery.</b> Place a ceramic capacitor from BATT to GND as close to the IC as possible.		
10	SYS	Power	<b>System power supply.</b> Place a ceramic capacitor from SYS to GND as close to the IC as possible.		





<b>ABSOLUTE MAXIMUM F</b>	RATINGS (1)
V <sub>IN</sub>	0.3V to +13V
All other pins to GND	0.3V to +6.0V
Continuous power dissipation (T <sub>A</sub>	
	1.25W
Junction temperature	150°C
Lead temperature (solder)	260°C
Storage temperature6	65°C to +150°C
Recommended Operating Co	onditions <sup>(3)</sup>
Recommended Operating Consumption Supply voltage (V <sub>IN</sub> )	onditions <sup>(3)</sup> 4.35V to 5.5V
Supply voltage (V <sub>IN</sub> )	4.35V to 5.5V (USB input)
Supply voltage (V <sub>IN</sub> )	4.35V to 5.5V (USB input)
Supply voltage (V <sub>IN</sub> )	4.35V to 5.5V (USB input) Up to 455mA
Supply voltage (V <sub>IN</sub> )	4.35V to 5.5V (USB input) Up to 455mA Up to 3A <sup>(5)</sup> Up to 455mA
Supply voltage (V <sub>IN</sub> )	4.35V to 5.5V (USB input) Up to 455mA Up to 3A <sup>(5)</sup> Up to 455mA

Thermal Resistance	e <sup>(4)</sup>	$oldsymbol{ heta}_{JA}$	$\boldsymbol{\theta}_{JC}$	
QFN-10 (2mmx2mm)		. 80	16	°C/W

#### NOTES:

- 1) Exceeding these ratings may damage the device.
- 2) The maximum allowable power dissipation is a function of the maximum junction temperature T<sub>J</sub> (MAX), the junction-to-ambient thermal resistance θ<sub>JA</sub>, and the ambient temperature T<sub>A</sub>. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P<sub>D</sub> (MAX) = (T<sub>J</sub> (MAX)-T<sub>A</sub>)/θ<sub>JA</sub>. Exceeding the maximum allowable power dissipation produces an excessive die temperature, causing the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- The device is not guaranteed to function outside of its operating conditions.
- 4) Measured on JESD51-7, 4-layer PCB.
- 5) Guaranteed by design



# **ELECTRICAL CHARACTERISTICS**

 $V_{IN}$  = 5.0V,  $V_{BATT}$  = 3.5V,  $T_A$  = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
Input Source and Battery P	rotection					
Input operation voltage	Vin		4.35	5	5.5	V
Battery input voltage (6)	V <sub>BATT</sub>				4.5	V
Input over-voltage protection trigger threshold	V <sub>IN_OVP</sub>	Input rising threshold	5.85	6	6.15	V
Input over-voltage protection recover threshold				350		mV
Input under-voltage lockout threshold	V <sub>IN_UVLO</sub>	Input rising threshold	3.8	3.9	4.0	V
Input under-voltage lockout threshold hysteresis				170		mV
Input vs. battery voltage headroom threshold	V <sub>HDRM</sub>	Input rising vs. battery	100	130	160	mV
Input vs. battery voltage headroom threshold hysteresis				85		mV
Battery under-voltage		I <sup>2</sup> C programmable range	2.4		3.1	V
lockout threshold	V <sub>BATT_UVLO</sub>	Falling, programmable, Reg01 bit[2:0] = 100	2.6	2.8	3.0	V
Battery under-voltage threshold hysteresis				210		mV
Battery over-voltage protection threshold	VBATT_OVP	Rising, higher than VBATT_REG		130		m)/
Battery over-voltage protection hysteresis				70		mV
Power Path Management						
System regulation voltage	$V_{SYS\_REG}$	$V_{IN} = 5.5V$ , $I_{SYS} = 10mA$ , $I_{CHG} = 0A$	4.55	4.65	4.75	V
		Reg00 bit[2:0] = 000 - 85mA	65	75	85	
Input current limit	I <sub>IN_LIM</sub>	Reg00 bit[2:0] = 001 - 130mA	102	116	130	mA
Imput current iimit	IIN_LIM	Reg00 bit[2:0] = 100 - 265mA	230	247	265	111/4
		Reg00 bit[2:0] = 111 - 455mA	400	428	455	
Input minimum voltage	VINI MINI	I <sup>2</sup> C programmable range	3.88		5.08	V
regulation	V <sub>IN_MIN</sub>	I <sup>2</sup> C setting V <sub>IN_MIN</sub> = 4.20V	4.10	4.20	4.30	v
IN to SYS switch on resistance	Ron_Q1	V <sub>IN</sub> = 5V, I <sub>SYS</sub> = 100mA		300	400	mΩ
Input quiescent current	lu, a	$V_{IN}$ = 5.5V, CE = L, charge enabled, $I_{CHG}$ = 0A, $I_{SYS}$ = 0A		630		^
input quiescent current	I <sub>IN_Q</sub>	$V_{IN}$ = 5.5V, CE = H, charge disabled		500		μΑ



# **ELECTRICAL CHARACTERISTICS** (continued)

 $V_{IN}$  = 5.0V,  $V_{BATT}$  = 3.5V,  $T_A$  = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
		$V_{IN} = 5V$ , CE = L, $I_{SYS} = 0A$ , $V_{BATT} = 4.3V$		32		
Battery quiescent current	Ibatt_q	V <sub>IN</sub> = 0V, CE = H, I <sub>SYS</sub> = 0A, V <sub>BATT</sub> = 4.35V, disable PCB OTP function, do not include the current from external NTC resistor		11	13	μA
Dattery quieceent current	ויייים יייים	V <sub>IN</sub> = 0V, CE = H, I <sub>SYS</sub> = 0A, V <sub>BATT</sub> = 4.35V, enable PCB OTP function, do not include the current from external NTC resistor		20	24	μ, ,
		$V_{BATT}$ = 4.5V, $V_{IN}$ = $V_{SYS}$ = GND, FET_DIS = 1, shipping mode		4	5.5	
Battery MOSFET on resistance	R <sub>ON_Q2</sub>	V <sub>IN</sub> < 2V, V <sub>BATT</sub> = 3.5V, I <sub>SYS</sub> = 100mA		100	150	mΩ
Battery current regulation in discharge mode	I <sub>DSCHG</sub>	I <sup>2</sup> C programmable range	400		3200 (6)	mA
Battery MOSFET switch leakage		$V_{BATT}$ = 4.5V, $V_{IN}$ = $V_{SYS}$ = GND, disconnect mode			1	μΑ
SYS reverse to BATT switch leakage		V <sub>SYS</sub> = 6V, V <sub>IN</sub> = 4.5V, V <sub>BATT</sub> = GND, CE = H			1	μA
Battery MOSFET disconnect	t <sub>INT</sub>	INT pull-low lasting time to turn off the battery MOSFET		16		
by INT (6)		Battery FET off lasting time before turn-on		4		S
Battery Charger						
Dattam, abanna waltana		I <sup>2</sup> C programmable range	3.600		4.545	
Battery charge voltage regulation	V <sub>BATT_REG</sub>	Reg04 bit[7:2] = 101000	4.179	4.20	4.221	V
		Reg04 bit[7:2] = 110010	4.328	4.35	4.372	
		$V_{IN}$ = 5V, $V_{BATT}$ = 3.8V, $I^2C$ programmable range	8		535 <sup>(6)</sup>	
Fast charge current	le :	V <sub>IN</sub> = 5V, V <sub>BATT</sub> = 3.8V, I <sub>CC_SETTING</sub> = 93mA	88	93	98	mA
	Icc	V <sub>IN</sub> = 5V, V <sub>BATT</sub> = 3.8V, I <sub>CC_SETTING</sub> = 246mA	232	248	263	ША
		V <sub>IN</sub> = 5V, V <sub>BATT</sub> = 3.8V, I <sub>CC_SETTING</sub> = 399mA	376	401	440	
Junction temperature regulation (6)	$T_{J\_REG}$	Reg06 bit[1:0] = 11 - 120°C		120		°C



# **ELECTRICAL CHARACTERISTICS** (continued)

 $V_{IN}$  = 5.0V,  $V_{BATT}$ =3.5V,  $T_A$  = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
		I <sup>2</sup> C programmable range	6		27	
Pre-charge current	I <sub>PRE</sub>	I <sub>PRE_SETTING</sub> = 6mA, Reg03 bit[1:0] = 00	2.5	4.7		mA
		I <sub>PRE_SETTING</sub> = 20mA, Reg03 bit[1:0] = 10	14	18	22	
		$I_{CC\_SETTING} \le 263 \text{mA}, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 00$	5	7	9	
		$I_{CC\_SETTING} \le 263 \text{mA}, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 01$	10	13.5	17	
		$I_{CC\_SETTING} \le 263 \text{mA}, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 10$	16	20	24	
Charge termination current	I <sub>TERM</sub>	I <sub>CC_SETTING</sub> ≤ 263mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 11	22	27	32	mA
threshold	HERM	I <sub>CC_SETTING</sub> ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 00	10	13.5	17	IIIA
		I <sub>CC_SETTING</sub> ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 01	22	27	32	
		I <sub>CC_SETTING</sub> ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 10	34	42	49	
		I <sub>CC_SETTING</sub> ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 11	46	55	64	
Charge termination current	<b>1</b>	I <sub>CC_SETTING</sub> ≤ 263mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 10	7.5	11	15	mΛ
threshold hysteresis	ITERM_HYS	I <sub>CC_SETTING</sub> ≤ 280mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 10	19	25	31	mA
Pre-charge to fast charge threshold	V <sub>BATT_PRE</sub>	V <sub>BATT</sub> rising, set V <sub>BATT_PRE</sub> = 3.0V	2.8	3.0	3.1	V
Pre-charge to fast charge threshold hysteresis				90		mV
Auto-recharge battery	V <sub>RECH</sub>	Reg04 bit[0] = 0	120	160	200	mV
voltage threshold	V RECH	Reg04 bit[0] = 1	260	300	365	111 V
Thermal Protection	T			ı		1
Thermal shutdown threshold (6)	T <sub>J_SHDN</sub>	Rising		150		°C
Thermal shutdown hysteresis <sup>(6)</sup>				20		°C
NTC output current	Intc	CE = L, NTC = 3V	-100	0	100	nA
NTC cold temperature rising threshold	Vcold	As a percentage of V <sub>DD</sub>	63	65	67	%
NTC cold temperature rising threshold hysteresis				30		mV



# **ELECTRICAL CHARACTERISTICS** (continued)

 $V_{IN}$  = 5V,  $T_A$  = 25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
NTC hot temperature falling threshold	V <sub>HOT</sub>	As a percentage of V <sub>DD</sub>	31	33	35	%
NTC hot temperature falling threshold hysteresis				70		mV
NTC hot temperature falling threshold for PCB OTP	V <sub>HOT_PCB</sub>	As a percentage of V <sub>DD</sub>	30	32	34	%
NTC hot temperature falling threshold hysteresis for PCB OTP				85		mV
Logic I/O Pin Characteristic	s <sup>(6)</sup>		•	•	•	
Low logic voltage threshold	VL				0.4	V
High logic voltage threshold	V <sub>H</sub>		1.3			V
I <sup>2</sup> C Interface (SDA, SCL) (6)						
Input high voltage level	V <sub>IH</sub>	V <sub>PULL_UP</sub> = 1.8V, SDA and SCL	1.3			V
Input low voltage level	VIL	V <sub>PULL_UP</sub> = 1.8V, SDA and SCL			0.4	V
Output low voltage level	V <sub>OL</sub>	I <sub>SINK</sub> = 5mA			0.4	V
I <sup>2</sup> C clock frequency	FscL				400	kHz
Clock Frequency and Watchdog Timer						
Clock frequency	Fclk			32		kHz
Watchdog timer	twdt	Programmable (Reg05 bit[5:4] = 11)		160		S

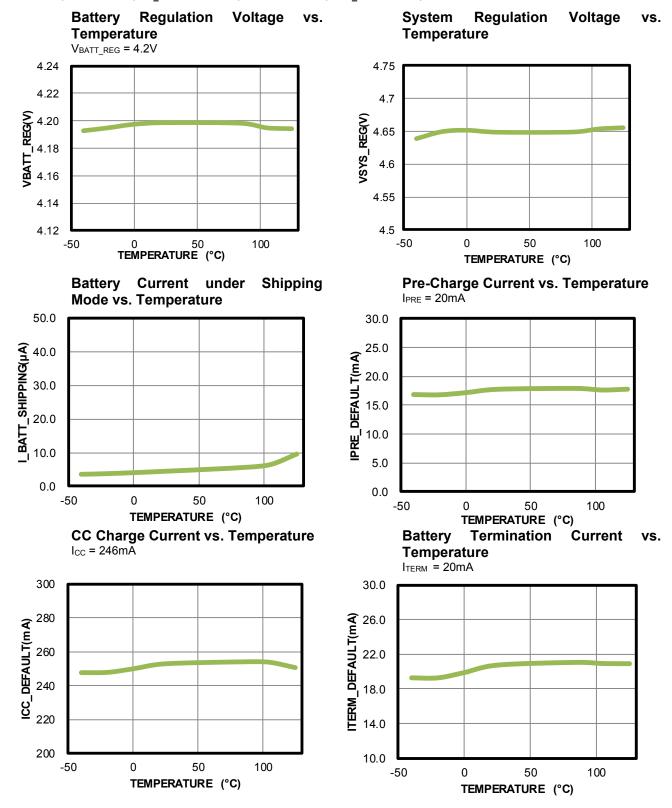
#### NOTE:

<sup>6)</sup> Guaranteed by design.



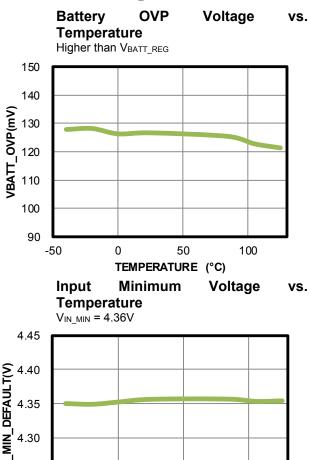
# TYPICAL PERFORMANCE CHARACTERISTICS

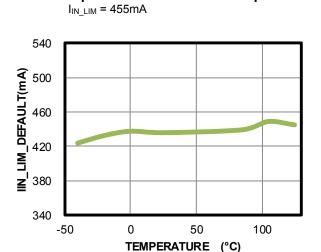
 $V_{IN}$  = 5V,  $T_A$  = 25°C,  $I_{IN\ LIM}$  = 455mA,  $I_{CC}$  = 246mA,  $V_{IN\ MIN}$  = 4.6V, unless otherwise noted.



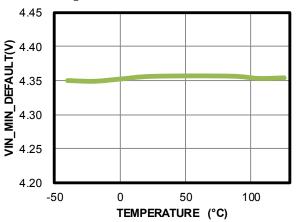


 $V_{IN}$  = 5V,  $T_A$  = 25°C,  $I_{IN\_LIM}$  = 455mA,  $I_{CC}$  = 246mA,  $V_{IN\_MIN}$  = 4.6V, unless otherwise noted.



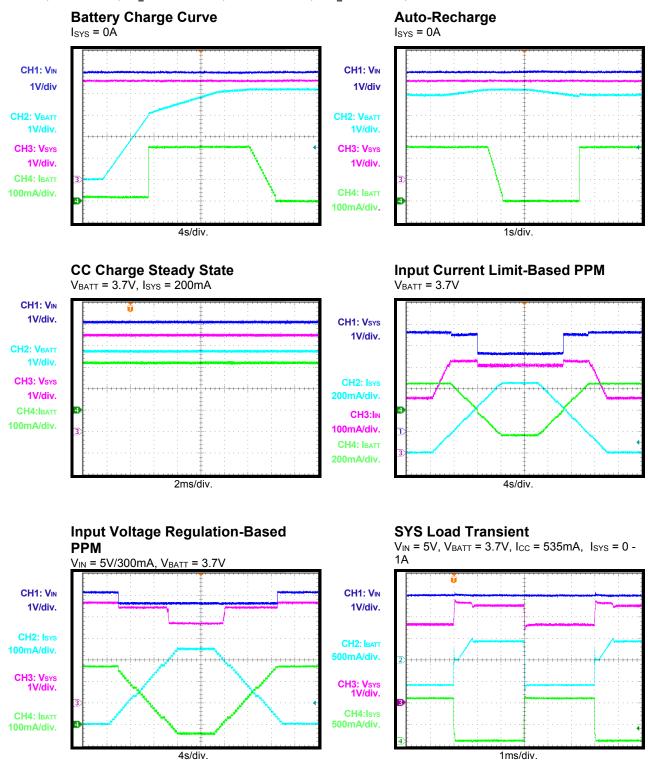


Input Current Limit vs. Temperature





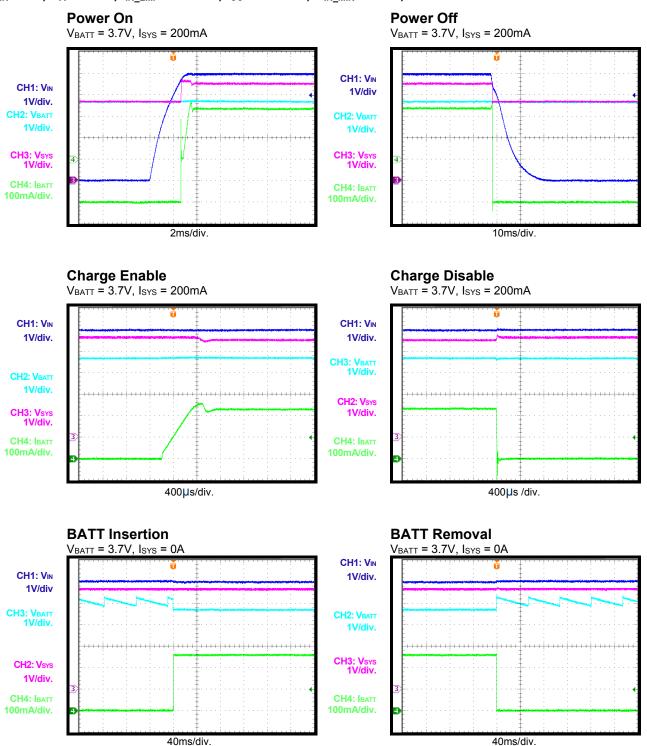
 $V_{IN}$  = 5V,  $T_A$  = 25°C,  $I_{IN\_LIM}$  = 455mA,  $I_{CC}$  = 246mA,  $V_{IN\_MIN}$  = 4.6V, unless otherwise noted.



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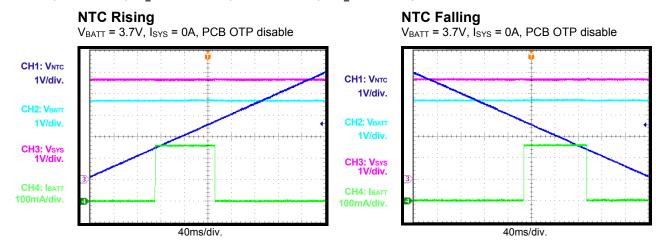
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CH1: VNTC

CH2: VBATT 1V/div.

CH3: Vsys

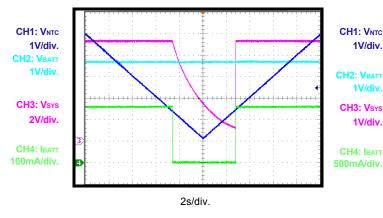
СН4: Іватт

1V/div.

1V/div.

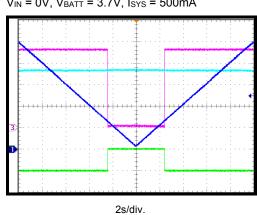


V<sub>BATT</sub> = 3.7V, I<sub>SYS</sub> = 0A



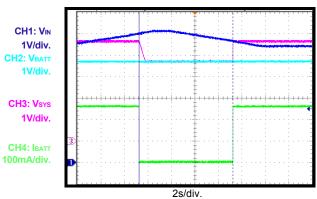
# PCB OTP @ Discharge Mode

 $V_{IN} = 0V$ ,  $V_{BATT} = 3.7V$ ,  $I_{SYS} = 500 \text{mA}$ 



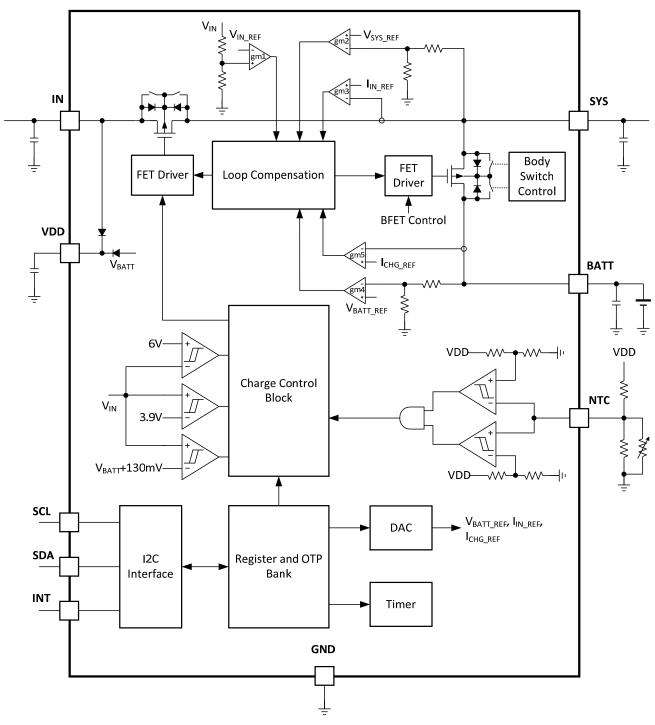
## **VIN OVP Operation**

 $V_{BATT} = 3.7V$ ,  $I_{SYS} = 0A$ 





## **BLOCK DIAGRAM**



**Figure 1: Function Block Diagram** 



#### **OPERATION**

The MP2664 is an I<sup>2</sup>C-controlled, single-cell, Liion or Li-polymer battery charger with complete power path management. The full-charge function features constant current pre-charge (PRE.C), constant current fast-charge (CC) and constant voltage (CV) regulation, charge termination, auto-recharge, and a built-in timer. The power path function allows the input source to power the system and charge the battery simultaneously. If there is a conflict in meeting both the system load and battery charging current, the IC reduces the charging current automatically or uses the battery as a supplemental power to satisfy the system load.

The IC integrates a  $300m\Omega$  LDO MOSFET between IN and SYS and a  $100m\Omega$  battery MOSFET between SYS and BATT.

In charging mode, the on-chip  $100m\Omega$  battery MOSFET works as a full-featured linear charger with constant current pre-charging, constant current fast-charging and constant-voltage charging, charge termination, auto-recharging, NTC monitoring, built-in timer control, and thermal protection. The charge current can be programmed via the  $I^2C$  interface. The IC limits the charge current when the die temperature exceeds the thermal regulation threshold ( $120^{\circ}C$  default).

In supplement mode, the  $100m\Omega$  battery MOSFET is fully turned on to connect the battery to the system load when the input power is not enough to power the system load. When the input is removed, the  $100m\Omega$  battery MOSFET is also fully turned on, allowing the battery to power up the system.

When the system load is satisfied, the remaining current is used to charge the smart power path management battery. The IC reduces the charging current or uses power from the battery to satisfy the system load when its demand is over the input power capacity.

Figure 2 shows the power path management structure of the MP2664.

#### **Power Path Management**

The IC employs a direct power path structure with the battery MOSFET decoupling the

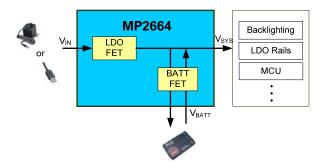


Figure 2: Power Path Management Structure

#### **Power Supply**

The internal bias circuit of the IC is powered from the higher voltage of IN or BATT. When IN or BATT rises above the respective undervoltage lockout (UVLO) threshold, the sleep comparator, battery depletion comparator, and the battery MOSFET driver are active. The I<sup>2</sup>C interface is ready for communication, and all registers are reset to the default value. The host can access all registers.

#### Input OVP and UVLO

The MP2664 has an input over-voltage protection (OVP) threshold and an input UVLO threshold. Once the input voltage exits the normal input voltage range, the Q1 MOSFET is turned off immediately.

When the input voltage is identified as a good source, a 200µs immunity timer becomes active. If the input power is still sufficient until the 200µs timer expires, the system starts up. Otherwise, Q1 remains off.

Figure 3 depicts the operation profile.

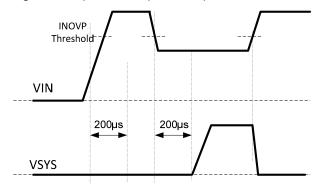


Figure 3: Input Power Detection Operation Profile

system from the battery, which allows for separate control between the system and the battery. The system is given priority to start up



even with a deeply discharged or missing battery. When the input power is available, even with a depleted battery, the system voltage is always regulated to  $V_{\text{SYS\_REG}}$  by the integrated LDO MOSFET.

As shown in Figure 2, the direct power structure is composed of a frond-end LDO MOSFET between IN and SYS and a battery MOSFET between SYS and BATT. The LDO MOSFET and battery MOSFET can be controlled by I<sup>2</sup>C.

Table 1: MOSFET Control by I<sup>2</sup>C

MOSFET On/Off	Hi-Z Mode and Charge Control			
Changed By Control	Set EN_HIZ to 1	Set CEB to 1		
LDO FET	OFF	х		
Battery FET (charging)	х	OFF		
Battery FET (discharging)	х	х		

NOTE: x indicates that the value does not matter.

The input LDO (using an LDO MOSFET) provides power to the system, which drives the system load directly and charges the battery through the battery MOSFET.

For the system voltage control, when the input voltage is higher than  $V_{SYS\_REG}$ , the system voltage is regulated to  $V_{SYS\_REG}$ . When the input

voltage is lower than V<sub>SYS\_REG</sub>, the LDO MOSFET is fully on with the input current limit.

#### **Battery Charge Profile**

The IC provides three main charging phases: constant current pre-charge, constant current fast-charge, and constant-voltage charge (see Figure 4).

- Phase 1 (constant current pre-charge): The IC is able to pre-charge the deeply depleted battery safely until the battery voltage reaches the pre-charge to the fast-charge threshold (V<sub>BATT\_PRE</sub>). The pre-charge current is programmable via Reg03 bit[1:0]. If V<sub>BATT\_PRE</sub> is not reached before the pre-charge timer (1hr) expires, the charge cycle is stopped, and a corresponding timeout fault signal is asserted.
- Phase 2 (constant current fast charge): When the battery voltage exceeds V<sub>BATT\_PRE</sub>, the IC enters a constant current fast-charge phase. The fast-charge current can be programmable via Reg02 bit[4:0].
- 3. Phase 3 (constant-voltage charge): When the battery voltage rises to the pre-programmable charge full voltage (VBATT\_REG) set via Reg04 bit[7:2], the charge mode changes from CC mode to CV mode, and the charge current begins to taper off.

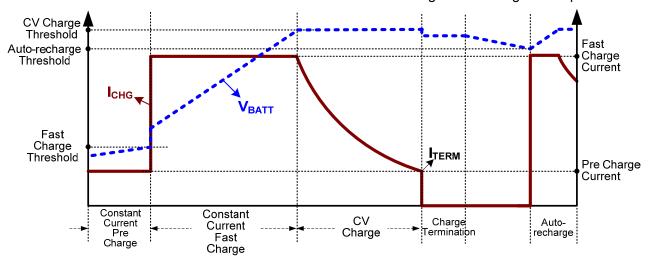


Figure 4: Battery Charge Profile



Assuming that the termination function (EN\_TERM) is set via Reg05 bit[6] = 1, the charge cycle is considered to be complete when the following conditions are valid:

- The charge current (I<sub>CHG</sub>) reaches the end of charge (EOC) current threshold (I<sub>TERM</sub>), and the 2.5ms delay timer is initiated.
- During the 2.5ms delay period, I<sub>BATT</sub> is always smaller than I<sub>TERM</sub> + I<sub>TERM HYS</sub>.

The charge status is marked as complete once the 2.5ms delay timer expires.

The charge current is terminated at the same time if TERM\_TMR is set via Reg05 [0] = 0; otherwise, the charge current continues tapering off.

If EN\_TERM = 0, the termination function is disabled, and the above actions will not occur (see Table 2).

**Table 2: Termination Function Selection Table** 

EN_TERM	TERM TMR	After I <sub>BATT</sub> CV n	
EN_IERWI	TERWI_TWR	Operation	Charge Status
0	х	Keep CV charge	Charge
1	0	Charge done	Charge done
1	1	Keep CV charge	Charge done

**NOTE:** x indicates that the value does not matter.

During the charging process, the actual charge current may be less than the register setting due to other loop regulations, such as dynamic power management (DPM) regulation (input voltage, input current) or thermal regulation. If the input current or the input voltage reach their limits during the CV charge, the charge-full termination is not influenced when the charge current is not as close to the EOC current specification.

A new charge cycle starts when the following conditions are valid:

- The input power is recycled
- Battery charging is enabled by the I<sup>2</sup>C
- Auto-recharge kicks in

Under the following conditions:

- No thermistor fault at NTC
- No safety timer fault
- No battery over-voltage
- · BATT FET is not forced to turn off

#### **Automatic Recharge**

When the battery is fully charged and the charging is terminated, the battery may be discharged due to system consumption or self-discharge. When the battery voltage is discharged below the recharge threshold and  $V_{\text{IN}}$  is still in the operation range, the IC begins another new charging cycle automatically without having to restart the charging cycle manually.

The auto-recharge function is valid only when EN\_TERM = 1 and TERM\_TMR = 0.

#### **Battery Over-Voltage Protection (OVP)**

The IC is designed with a built-in battery overvoltage limit about 130mV higher than  $V_{BATT\_REG}$ . When a battery over-voltage event occurs, the IC suspends the charging immediately and asserts a fault.

# Input Current and Input Voltage-Based Power Management

To meet the input source (usually USB) maximum current-limit specification, the IC uses input current-based power management by monitoring the input current continuously. The total input current limit can be programmed via the I<sup>2</sup>C to prevent the input source from overloading.

If the pre-set input current limit is higher than the rating of the input source, back-up input voltage-based power management also works to prevent the input source from being overloaded. If either the input current limit or the input voltage limit is reached, the Q1 MOSFET between IN and SYS are regulated so that the total input power is limited. As a result, the system voltage drops. Once the system declines to the minimum value of 4.56V or  $V_{\rm IN}$  -  $160 \, {\rm mV}$ , the charge current is reduced to prevent the system voltage from dropping further.



Voltage-based DPM regulates the input voltage to  $V_{\text{IN\_MIN}}$  when the load is over the input power capacity.  $V_{\text{IN\_MIN}}$  set via the I<sup>2</sup>C should be at least 400mV higher than  $V_{\text{BATT\_REG}}$  to ensure the stable operation of the regulator.

## **Battery Supplement Mode**

The charge current is reduced to keep the input current or input voltage in regulation when DPM occurs. If the charge current is at zero, and the input source is still overloaded due to a heavy system load, the system voltage starts to fall off. Once the system voltage falls below the battery voltage, the IC enters battery supplement mode. When the system voltage is 30mV below the battery voltage, ideal diode mode is enabled. The battery MOSFET is regulated to maintain  $V_{\text{BATT}}$  -  $V_{\text{SYS}}$  at 22.5mV. If the supplement current I<sub>DSCHG</sub> \* R<sub>ON BATT</sub> is higher than 22.5mV, the battery MOSFET is fully turned on to keep the ideal forward voltage. When the system load decreases, once V<sub>SYS</sub> is higher than V<sub>BATT</sub> + 20mV, ideal diode mode is disabled.

Figure 5 shows the dynamic power management and battery supplement mode operation profile.

When  $V_{\text{IN}}$  is not available, the IC operates in discharge mode, and the battery MOSFET is always fully on to reduce loss.

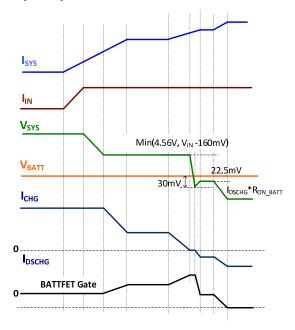


Figure 5: Dynamic Power Management and Battery Supplement Operation Profile

#### **Battery Regulation Voltage**

The battery voltage for the constant-voltage regulation phase is  $V_{BATT\_REG}$ . When  $V_{BATT\_REG}$  is 4.2V, it has a  $\pm 0.5\%$  accuracy over the ambient temperature range of 0°C to +50°C. When the battery is removed, the BATT voltage is between  $V_{BATT\_REG}$  -  $V_{RECH}$  and  $V_{BATT\_REG}$ .

#### **Thermal Regulation and Thermal Shutdown**

monitors the internal iunction temperature continuously to maximize power delivery and prevent the chip from overheating. When the internal junction temperature reaches the pre-set limit of T<sub>J REG</sub> (default 120°C), the IC reduces the charge current to prevent higher dissipation. multiple power The regulation thresholds from 60°C to 120°C help system design meet the thermal requirement in different applications. The junction temperature regulation threshold can be set via Reg06 bit[1:0].

When the junction temperature reaches 150°C, both Q1 and Q2 are turned off.

## Negative Temperature Coefficient (NTC) Temperature Sensor

NTC allows the IC to sense the battery temperature using the thermistor usually available in the battery pack to ensure a safe operating environment for the chip. A resistor with an appropriate value should be connected from VDD to NTC, and the thermistor should be connected from NTC to ground. The voltage on NTC is determined by the resistor divider, whose divide ratio depends on the temperature. The IC sets a pre-determined upper and lower bound of the divide ratio internally for NTC cold and NTC hot. In the MP2664, the I<sup>2</sup>C default setting is the PCB OTP. The function can be changed through the I<sup>2</sup>C (see Table 3).

**Table 3: NTC Function Selection Table** 

l <sup>2</sup> C	Control	
EN_NTC	EN_PCB OTP	Function
0	х	Disable
1	1	NTC
1	0	PCB OTP



When PCB OTP is selected, if the NTC voltage is lower than the NTC hot threshold, both the LDO MOSFET and battery MOSFET are off. The PCB OTP fault sets the NTC\_FAULT status (Reg08 bit[1]) to 1 to indicate the fault. Operation resumes once the NTC voltage is higher than the NTC hot threshold.

The NTC function only works in charge mode. Once the NTC voltage goes out of the divide ratio (the temperature is outside the safe operating range), the IC stops the charging and reports it on the status bits. Charging resumes automatically after the temperature falls back to the safe range.

#### **Safety Timer**

The IC provides both a pre-charge and a fast-charge safety timer to prevent extended charging cycles due to abnormal battery conditions. The safety timer is one hour when the battery voltage is below  $V_{BATT\_PRE}$ . The fast-charge safety timer begins when the battery enters constant current fast charging. The fast-charge safety timer can be programmed through the I $^2$ C. The safety timer feature can be disabled via the I $^2$ C.

The following actions can restart the safety timer:

- A new charge cycle is kicked in
- Reg01 bit[3] is written from 0 to 1 (charge enable)
- Reg05 bit[3] is written from 0 to 1 (safety timer enable)
- Reg01 bit[7] is written from 0 to 1 (software reset)

#### **Host Mode and Default Mode**

The IC is a host-controlled device. After the power-on reset, the IC starts in the watchdog timer expiration state or default mode. All of the registers are in the default settings.

Any write to the IC changes it to host mode. All charge parameters are programmable. If the watchdog timer (Reg05 bit[5:4]) is not disabled, the host must reset the watchdog timer regularly by writing 1 to the Reg01 bit[6] before the watchdog timer expires to keep the device in host mode. Once the watchdog timer expires, the IC returns to default mode. The watchdog timer limit can also be programmed or disabled

by the host control. When there is no  $V_{IN}$ , the watchdog timer is suspended (see Figure 10).

The operation can also be changed to default mode when one of the following conditions occur:

- Refresh input without battery
- Re-insert battery with no V<sub>IN</sub>
- Register reset Reg01 bit[7] is reset

#### **Battery Discharge Function**

If battery is connected and the input source is missing, the battery MOSFET is fully on when  $V_{BATT}$  is above the  $V_{BATT\_UVLO}$  threshold. The  $100m\Omega$  battery MOSFET minimizes conduction loss during discharge. The quiescent current of the IC is as low as  $11\mu A$  in this mode. The low on resistance and low quiescent current help extend the running time of the battery.

#### **Over-Discharge Current Protection**

The IC has an over-discharge current protection in discharge mode and supplement mode. Once  $I_{BATT}$ exceeds the programmable discharge current limit (default 1.785A), the battery MOSFET is turned off after a 60µs delay. and the MP2664 enters hiccup mode in overcurrent protection (OCP). The discharge current can be programmed high to 3.2A through the I<sup>2</sup>C. If the discharge current goes high to reach the internal fixed current limit (about 3.7A), the battery MOSFET is turned off and starts hiccup mode immediately.

Similarly, when the battery voltage falls below the programmable  $V_{BATT\_UVLO}$  threshold (default 2.8V), the battery MOSFET is turned off to prevent over-discharge.

## System Short-Circuit Protection (SCP)

The MP2664 features SYS node short-circuit protection (SCP) for the IN to SYS path and the BATT to SYS path.

The system voltage is monitored continuously. If  $V_{SYS}$  is lower than 1.5V, the system (SCP) for the IN to SYS path and the BATT to SYS path are active.  $I_{DSCHG}$  is decreased to half of the original value.



- 1) IN to SYS path: Once I<sub>IN</sub> is over the protection threshold, both the LDO MOSFET and the BATT MOSFET are turned off immediately, and the IC enters hiccup mode. Otherwise, the max current limit and the setting input current limit are not reached, and I<sub>IN</sub> is regulated at I<sub>IN\_LIM</sub>. Hiccup mode also starts after a 60µs delay. The interval of the hiccup mode is 800µs.
- 2) BATT to SYS path: Once IBATT is over the 3.7A protection threshold, both the LDO MOSFET and the BATT MOSFET are turned off immediately, and the IC enters hiccup mode. When the battery discharge current limit threshold is reached, hiccup mode starts after a 60µs delay. The interval of the hiccup mode is 800µs.

If a system short-circuit occurs when both the input and battery are present, the protection mechanism of both paths work, with the faster one dominating the hiccup operation (see Figure 13).

#### Interrupt to Host (INT)

The IC has an alert mechanism that can output an interrupt signal via INT to notify the system of the operation by outputting a 256µs low-state INT pulse. Any of the below events can trigger the INT output:

- · Good input source detected
- UVLO or input over-voltage protection (OVP) charge completed
- Charging status change
- Any fault in Reg08 (watchdog timer fault, input fault, thermal fault, safety timer fault, battery OVP fault, NTC fault)

When any fault occurs, the IC sends out an INT pulse and latches the fault state in Reg08. After the IC exits the fault state, the fault bit can be released to 0 after the host reads Reg08. The NTC fault is not latched and always reports the current thermistor conditions.

Note that the INT needs the external pull-up resistor for its open-drain connection. The resistance should not be lower than  $200k\Omega$ .

#### **Battery Disconnect Function**

In applications where the battery is not removable, it is essential to disconnect the battery from the system for two reasons: to prevent excessive capacity discharge when the device is in shipping or storage mode, and to allow the system power to reset.

The MP2664 provides both shipping mode and system reset mode for different application requirements.

The register bit FET\_DIS (Reg06 bit[5]), allows the IC to enter shipping mode. During normal operation, the battery MOSFET is turned on, and this bit is 0. If this bit is set to 1 through the I<sup>2</sup>C, the battery MOSFET is turned off, and the MP2664 enters shipping mode. The FET\_DIS bit is reset to 0 automatically after the battery MOSFET is turned off (see Figure 6).

The IC can exit shipping mode by pulling INT down. When the IC is in shipping mode and only the battery is present, pull INT down by pushing the push button (PB) to wake the MP2664 up from shipping mode (see Table 4).

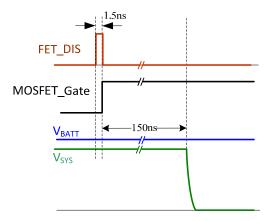


Figure 6: Time Delay from when FET\_DIS is written to 1 to the Battery MOSFET Turning Off



Table 4: Exit the Shipping Mode with BATT **Present Only** 

	INT Signal	IC Exits Shipping Mode
Case 1	INT = low twice with the rising edge >600ns	At once
Case 2	INT = low once with the rising edge >600ns	After 4s
Case 3	INT = low for 4s	After 4s
Case 4	INT = low with the rising edge in ms level	At once

The MP2664 can also wake up from shipping mode when a valid V<sub>IN</sub> powers on (see Table 5). After V<sub>IN</sub> is preset, the MP2664 pulls INT low to indicate the event "Good input source detected" if V<sub>IN</sub> is in the operating range. Then, the MP2664 can be woken up from shipping mode by the INT signal (see Figure 7).

Table 5: Exiting Shipping Mode when VIN Powers On

	INT Signal	IC Exits Shipping Mode
Case 1	INT= low twice with the rising edge >600ns	At once
Case 2	INT= low once with the rising edge >600ns	After 4s
Case 3	INT = low with the rising edge in ms level	At once

If FET DIS is set to 1 during shipping mode, the IC can wake up after keeping INT low for 4s. In this case, the FET DIS bit cannot be reset to 0 automatically—it must be reset to 0 manually through the I2C.

The IC can use INT to cut off the path from the battery to the system when a system reset is needed.

Once the logic at INT is set to low for more than 16s, the battery is disconnected from the system by turning off the battery MOSFET.

The off state lasts for 4s, and then the battery MOSFET is turned on automatically. The system is powered by the battery again. During the 4s off period, the INT pin voltage level can be high or low. The IC can reset the system by controlling INT (see Figure 8).

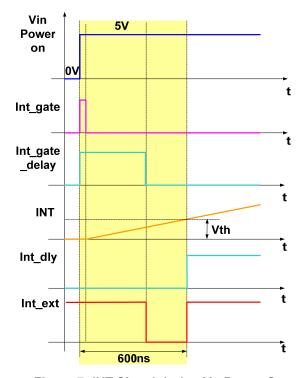
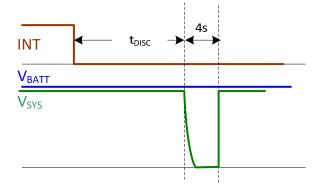


Figure 7: INT Signal during V<sub>IN</sub> Power On



**Figure 8: System Reset Function Operation Profile** 



# I<sup>2</sup>C REGISTER MAP

IC Address: 09H (reserved some trim options)

Input Source Control Register/Address: 00H (Default: 0100 1111)

Bit	Symbol	Description	Read/Write	Default		
Bit 7	EN_HIZ (7)	0: disable 1: enable	r/w	Disable (0)		
Input Minin	Input Minimum Voltage Regulation					
Bit 6	V <sub>IN_MIN</sub> [3]	640mV				
Bit 5	V <sub>IN_MIN</sub> [2]	320mV	-/	Offset: 3.88V		
Bit 4	V <sub>IN_MIN</sub> [1]	160mV	r/w	Range: 3.88V - 5.08V Default: 4.60V (1001)		
Bit 3	VIN_MIN [0]	80mV				
Input Curre	ent Limit					
Bit 2	I <sub>IN_LIM</sub> [2]	000: 85mA 001: 130mA 010: 175mA				
Bit 1	lin_Lim [1]	011: 220mA 100: 265mA	r/w	455mA (111)		
Bit 0	IIN_LIM [0]	101: 310mA 110: 355mA 111: 455mA				

#### NOTE:

## Power-On Configuration Register/Address: 01H (Default: 0000 0100)

Bit	Symbol	Description	Read/Write	Default	
Bit 7	Register reset	0: keep current setting 1: reset	r/w	Keep current setting (0)	
Bit 6	I <sup>2</sup> C watchdog timer reset	0: normal 1: reset	r/w	Normal (0)	
Bit 5	Reserved		r/w Reserved		
Bit 4	Reserved		r/w	Reserved	
Charger Co	nfiguration				
Bit 3	CEB	0: charge enabled 1: charge disabled	r/w	Charge enabled (0)	
Battery UVI	_O Threshold				
Bit 2	V <sub>BATT_UVLO</sub> [2]	0.4V		Offset: 2.4V	
Bit 1	V <sub>BATT_UVLO</sub> [1]	0.2V	r/w	Range: 2.4V - 3.1V	
Bit 0	VBATT_UVLO [0]	0.1V		Default: 2.8V (100)	

<sup>7)</sup> This bit only controls the on and off of the LDO MOSFET.





## Charge Current Control Register/Address: 02H (Default: 0000 1110)

Bit	Symbol	Description	Read/Write	Default	
Bit 7	Reserved		r/w	Reserved	
Bit 6	Reserved		r/w	Reserved	
Bit 5	Reserved		r/w	Reserved	
Fast-Char	Fast-Charge Current Setting				
Bit 4	Icc [4]	272mA			
Bit 3	I <sub>CC</sub> [3]	136mA		Offset: 8mA Range: 8mA - 535mA	
Bit 2	I <sub>CC</sub> [2]	68mA	r/w		
Bit 1	I <sub>CC</sub> [1]	34mA		Default: 246mA (01110)	
Bit 0	I <sub>CC</sub> [0]	17mA	]	(35)	

# Pre-Charge/Termination Current/Address: 03H (Default: 0100 1010)

Bit	Symbol	Description	Read/Write	Default	
Bit 7	Reserved		r/w	Reserved	
BATT to S	SYS Discharge Current	Limit			
Bit 6	IDSCHG [3]	1600mA		Offset: 200mA	
Bit 5	I <sub>DSCHG</sub> [2]	800mA		Range: 400mA - 3.2A Valid range: 0001 -	
Bit 4	I <sub>DSCHG</sub> [1]	400mA	r/w	1111	
Bit 3	IDSCHG [0]	200mA		Default: 2000mA (1001)	
PCB OTF	<sup>2</sup> Enable				
Bit 2	Bit 2 EN_PCB OTP 0: enable 1: disable		r/w	Enable(0)	
Pre-Char	ge Current				
Bit 1	I <sub>PRE</sub> [1]	14mA		Offset: 6mA	
Bit 0	I <sub>PRE</sub> [0]	7mA	r/w	Range: 6mA - 27mA Default: 20mA (10) IPRE[1:0] also sets termination current	



## Charge Voltage Control Register/Address: 04H (Default: 1010 0011)

Bit	Symbol	Description	Read/Write	Default		
Battery Reg	Battery Regulation Voltage					
Bit 7	V <sub>BATT_REG</sub> [5]	480mV				
Bit 6	V <sub>BATT_REG</sub> [4]	240mV		Offset: 3.60V		
Bit 5	V <sub>BATT_REG</sub> [3]	120mV	r/w	Range: 3.60V - 4.545V		
Bit 4	V <sub>BATT_REG</sub> [2]	60mV	] 1/w	Default: 4.2V		
Bit 3	V <sub>BATT_REG</sub> [1]	30mV		(101000)		
Bit 2	VBATT_REG [0]	15mV				
Pre-Charge	to Fast Charge Thres	hold				
Bit 1	VBATT_PRE	0: 2.8V 1: 3.0V	r/w	3.0V (1)		
Battery Red	Battery Recharge Threshold (below V <sub>BATT_REG</sub> )					
Bit 0	V <sub>RECH</sub>	0: 150mV 1: 300mV	r/w	300mV (1)		

# Charge Termination/Timer Control Register/Address: 05H (Default: 0100 1010)

Bit	Symbol	Description	Read/Write	Default	
Bit 7	Reserved		r/w	Reserved	
Termination	n Setting (the terminati	on is allowed or not)			
Bit 6	EN_TERM	0: disable 1: enable	r/w	Enabled (1)	
I <sup>2</sup> C Watchd	og Timer Limit				
Bit 5	WATCHDOG [1]	00: disable timer 01: 40s	r/w	Disable timer (00)	
Bit 4	WATCHDOG [0]	10: 80s 11: 160s	17 W	Disable timer (00)	
Safety Time	er Setting				
Bit 3	EN_TIMER	0: disable 1: enable	r/w	Enable timer (1)	
Fast-Charg	e Timer				
Bit 2	CHG_TMR [1]	00: 3hrs 01: 5hrs	r/w	Ehro (01)	
Bit 1	CHG_TMR [0]	10: 8hrs 11: 12hrs	17 W	5hrs (01)	
Termination charge term		n TERM_TMR is enabled, the IC wi	ill not suspend th	ne charge current after	
Bit 0	TERM_TMR	0: disable 1: enable	r/w	(0)	



## Miscellaneous Operation Control Register/Address: 06H (Default: 0100 1011)

Bit	Symbol	Description	Read/Write	Default		
Bit 7	Reserved		r/w	Read/write		
Bit 6	Reserved		r/w	This bit must be set to 0		
Bit 5	FET_DIS (8)	0: enable 1: turn off	r/w	Enabled (0)		
Bit 4	Reserved		r/w	(0)		
Bit 3	EN_NTC	0: disable 1: enable	r/w	Enabled (1)		
Bit 2	Reserved		r/w			
Thermal Re	Thermal Regulation Threshold					
Bit 1	T <sub>J_REG</sub> [1]	00: 60°C 01: 80°C	r/w	120°C (11)		
Bit 0	T <sub>J_REG</sub> [0]	10: 100°C 11: 120°C	17 VV	120 0 (11)		

#### NOTE:

## System Status Register/Address: 07H (Default: 0000 0000)

Bit	Symbol	Description	Read/Write	Default		
Bit 7	Reserved		r	Reserved		
Revision						
Bit 6	Rev [1]	Davisian number	_	(00)		
Bit 5	Rev [0]	Revision number	ľ	(00)		
Bit 4	CHG_STAT [1]	00: not charging 01: pre-charge	r	Not charging (00)		
Bit 3	CHG_STAT [0]	10: charge 11: charge done	I	140t Gharging (00)		
Bit 2	PPM_STAT	0: no PPM 1: in PPM	r	No PPM (0) (no power-path management happens)		
Bit 1	PG_STAT	0: power fail 1: power good	r	Not power good (0)		
Bit 0	THERM_STAT	0: no thermal regulation 1: in thermal regulation	r	Normal (0)		

<sup>8)</sup> This bit controls the on and off of the battery MOSFET, including the charging and discharging.





Fault Register/Address: 08H (Default: 0000 0000)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Reserved		r	Reserved
Bit 6	WATCHDOG_FAULT	0: normal 1: watchdog timer expiration	r	Normal (0)
Bit 5	VIN_FAULT	0: normal 1: input fault (OVP or bad source)	r	Normal (00)
Bit 4	THEM_SD	0: normal 1: thermal shutdown	r	
Bit 3	BAT_FAULT	0: normal 1: battery OVP	r	Normal (0)
Bit 2	STMR_FAULT	0: normal 1: safety timer expiration	r	Normal (0)
Bit 1	NTC_FAULT [1]	0: normal 1: NTC hot	,	Normal (00)
Bit 0	NTC_FAULT [0]	0: normal 1: NTC cold		Normal (00)



# **OTP MAP**

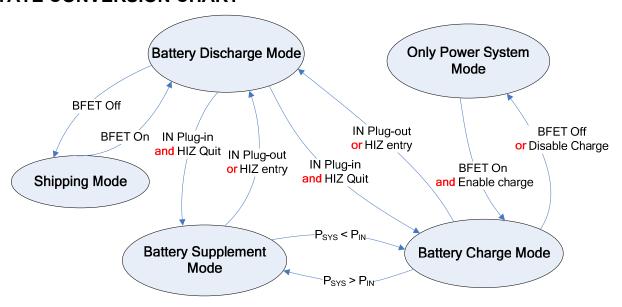
#	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0x02	N/A Icc: 8mA - 535mA / 17mA				A step			
0x03	N/A				EN_PCB_OTP	lρ	RE	
0x04	V <sub>BATT_REG</sub> : <b>3.6V - 4.545V / 15mV</b> step				N.	/A		
0x05	N/A		WATC	CHDOG N/A				

# **OTP DEFAULT**

OTP Items	Default	
Icc	246mA	
IPRE	20mA	
V <sub>BATT_REG</sub>	4.2V	
WATCHDOG	Disable timer	
EN_PCB OTP	Enable	



## STATE CONVERSION CHART



**Figure 9: State Machine Conversion** 



## **CONTROL FLOW CHART**

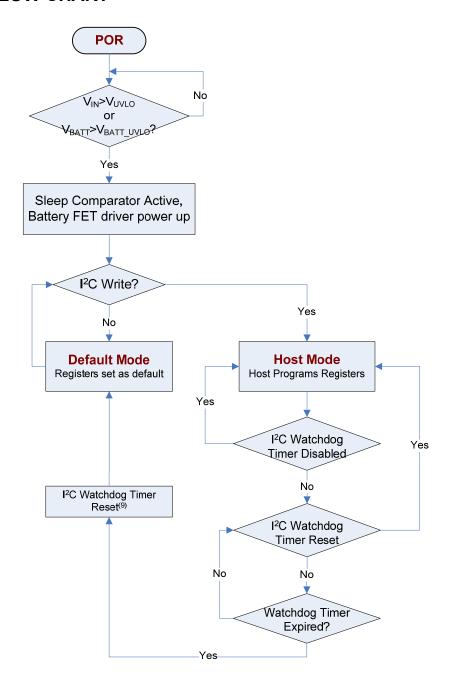


Figure 10: Default Mode and Host Mode Selection (10)

#### NOTES:

- 9) Once the watchdog timer expires, the I²C watchdog timer must be reset, or the watchdog timer is not valid in the next cycle.
   10) The watchdog timer is held when V<sub>IN</sub> is not present.



# **CONTROL FLOW CHART** (continued)

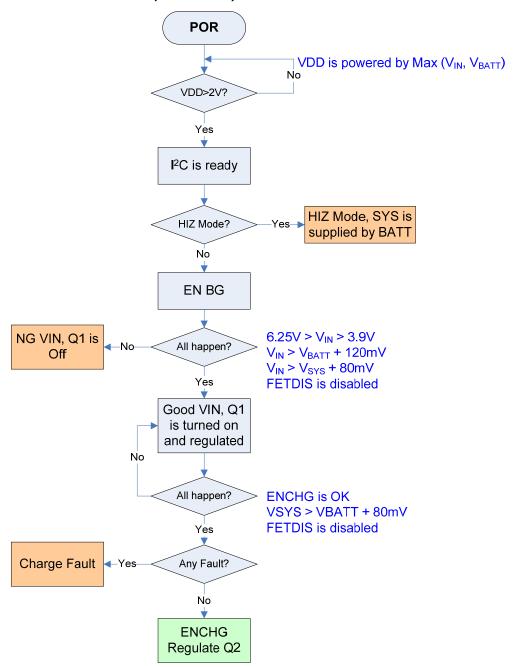


Figure 11: Input Power Start-Up Flow Chart



# **CONTROL FLOW CHART** (continued)

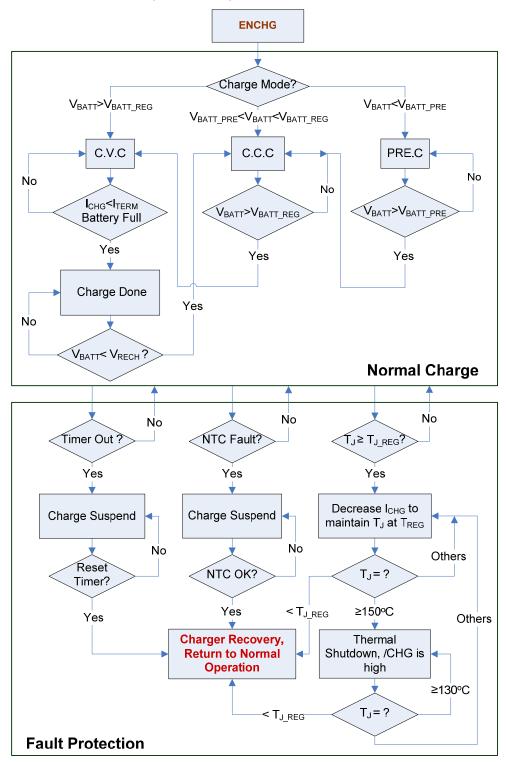


Figure 12: Charging Process



# **CONTROL FLOW CHART** (continued)

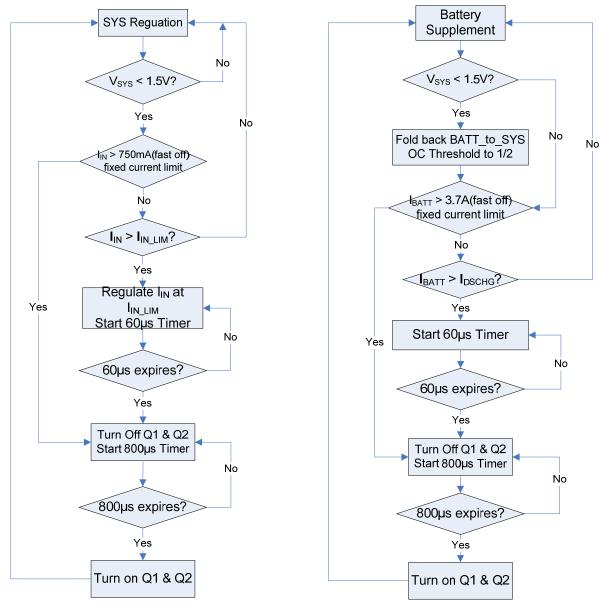


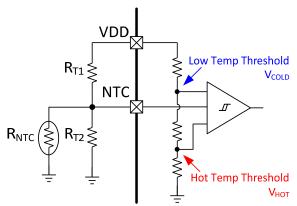
Figure 13: System Short-Circuit Protection



## APPLICATION INFORMATION

#### Selecting a Resistor for the NTC Sensor

NTC uses a resistor divider from the input source (VDD) to sense the battery temperature. The two resistors ( $R_{T1}$  and  $R_{T2}$ ) allow the high temperature limit and low temperature limit to be programmed independently (see Figure 14). In other words, the IC can fit most types of NTC resistors and different temperature operation range requirements with the two extra resistors.



**Figure 14: NTC Function Block** 

For a given NTC thermistor,  $R_{T1}$  and  $R_{T2}$  depend on the type of NTC resistor used and can be calculated with Equation (1) and Equation (2):

$$R_{\text{T2}} = \frac{\left(V_{\text{COLD}} - V_{\text{HOT}}\right) \times R_{\text{NTCH}} \times R_{\text{NTCL}}}{\left(V_{\text{HOT}} - V_{\text{COLD}}V_{\text{HOT}}\right) \times R_{\text{NTCL}} - \left(V_{\text{COLD}} - V_{\text{COLD}}V_{\text{HOT}}\right) \times R_{\text{NTCH}}} \quad \textbf{(1)}$$

$$R_{T1} = \frac{1 - V_{COLD}}{V_{COLD}} \times (R_{T2} // R_{NTCL})$$
 (2)

Where  $R_{\text{NTCH}}$  is the value of the NTC resistor at the high temperature of the required temperature operating range, and  $R_{\text{NTCL}}$  is the value of the NTC resistor at a low temperature.

For example, for thermistor NCP18XH103,  $R_{NTCL}$  is 27.219k $\Omega$  at 0°C, and  $R_{NTCH}$  is 4.161k $\Omega$  at 50°C. Equation (1) and Equation (2) determine that  $R_{T1}$  = 7.01k $\Omega$  and  $R_{T2}$  = 27.21k $\Omega$  (assuming that the NTC window is between 0°C and 50°C and using the  $V_{COLD}$  and  $V_{HOT}$  values from the EC table on page 8).

## Selecting the External Capacitor

Like most low-dropout regulators, the MP2664 requires external capacitors for regulator stability and voltage spike immunity. The MP2664 is designed specifically for portable applications requiring a minimal board space and small components. These capacitors must be selected correctly for optimal performance.

An input capacitor is required for stability. Connect a  $1\mu F$  (minimum) capacitor between IN and GND for stable operation over the entire load current range. There can be more output capacitance than input as long as the input is at least  $1\mu F$ .

The IC is designed specifically to work with a very small ceramic output capacitor. A >2.2 $\mu$ F ceramic capacitor with X5R or X7R type dielectrics is suitable in the MP2664 application circuit. For the MP2664, the output capacitor should be connected between SYS and GND with thick traces and a small loop area.

A capacitor from BATT to GND is necessary for the MP2664. A >2.2 $\mu$ F ceramic capacitor with X5R or X7R type dielectrics is suitable for the application circuit.

A capacitor between VDD and GND is used to stabilize the VDD voltage to power the internal control and logic circuit. The typical value of this capacitor is 100nF.

## **PCB Layout Guidelines**

Efficient PCB layout is critical for stable operation. For best results, follow the guidelines below.

- Place the external capacitors as close to the IC as possible to ensure the smallest input inductance and ground impedance.
- Place the PCB trace connecting the capacitor between VDD and GND very close to the IC.
- 3. Keep the GND for the I<sup>2</sup>C wire clean and away from GND.
- 4. Place the I<sup>2</sup>C wire in parallel.



## TYPICAL APPLICATION CIRCUIT

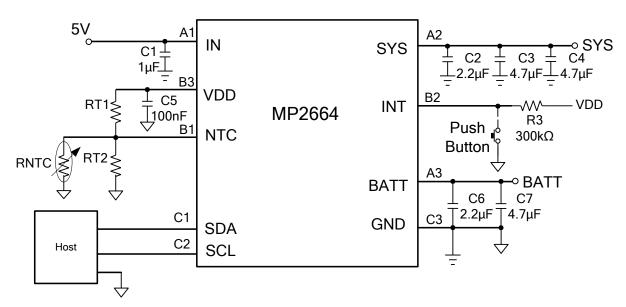


Figure 15: MP2664 Typical Application Circuit with 5V Input

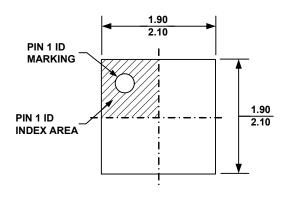
Table 6: Key BOM from Figure 15

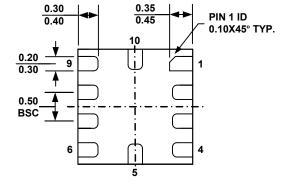
Qty	Ref	Value	Description	Package	Manufacture
1	C1	1µF	Ceramic Capacitor;16V; X5R or X7R	0603	Any
2	C2, C6	2.2µF	Ceramic Capacitor;16V; X5R or X7R	0603	Any
1	C3, C4, C7	4.7µF	Ceramic Capacitor; 16V; X5R or X7R	0603	Any
1	C5	100nF	Ceramic Capacitor;16V; X5R or X7R	0603	Any



## **PACKAGE INFORMATION**

## QFN-10 (2mmx2mm)



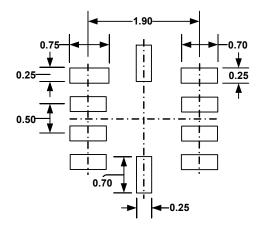


**TOP VIEW** 

**BOTTOM VIEW** 



**SIDE VIEW** 



RECOMMENDED LAND PATTERN

#### NOTE:

- 1) ALL DIMENSIONS ARE IN MILLIMETERS.
- 2) EXPOSED PADDLE SIZE DOES NOT INCLUDE MOLD FLASH.
- 3) LEAD COPLANARITY SHALL BE 0.10 MILLIMETER MAX.
- 4) JEDEC REFERENCE IS MO-220, VARIATION VCCD.
- 5) DRAWING IS NOT TO SCALE.

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